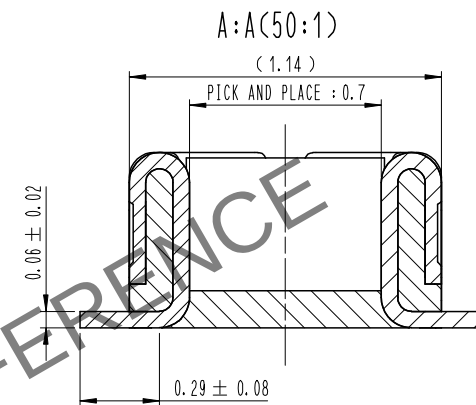
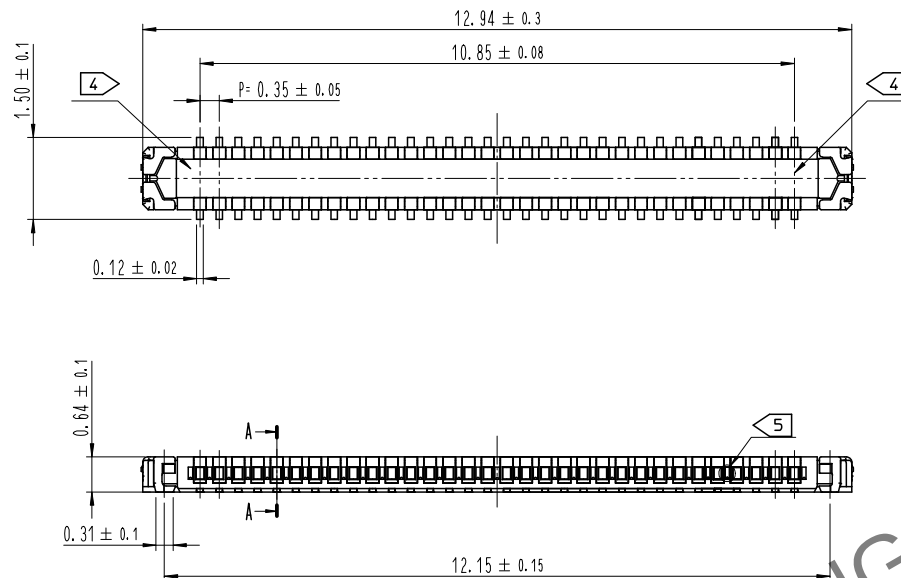
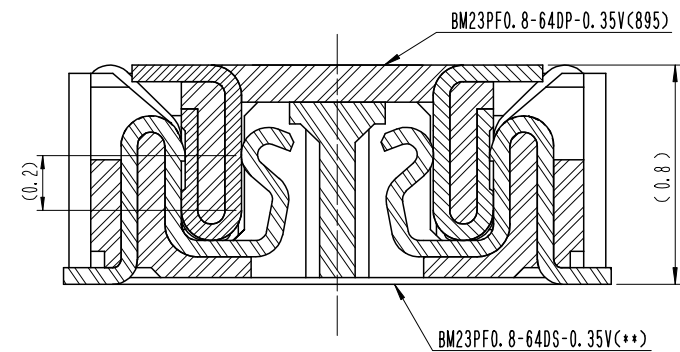


訂正事項									
△數	訂正事項	擔當	檢圖	年月日	△數	訂正事項	擔當	檢圖	年月日
COUNT	DESCRIPTION OF REVISIONS	B Y	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	B Y	CHKD	DATE
△				.	△				.
△				.	△				.
△				.	△				.



ENGAGEMENT FIGURE (50:1)

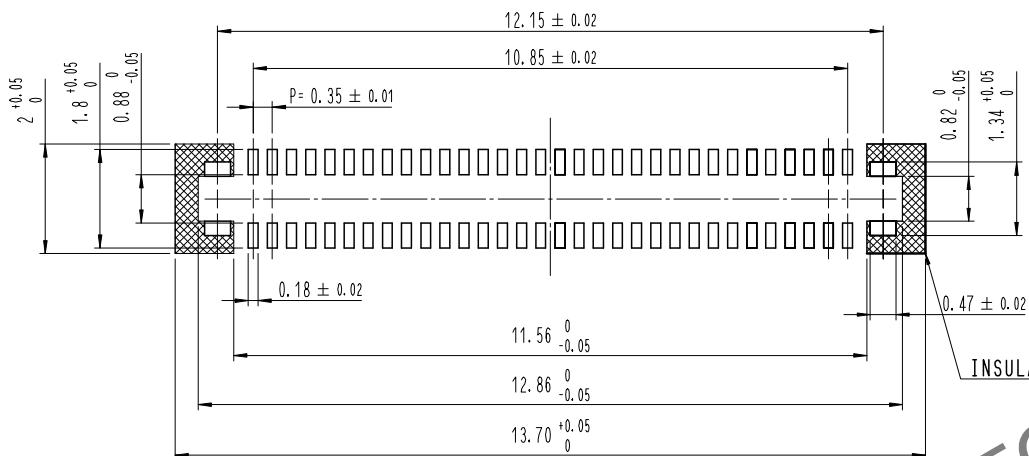


NOTE 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.

2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μ m MIN.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDER PLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
3. METAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDERPLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
4. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
5. A PART OF THE WALL COULD BE NOTCHED.

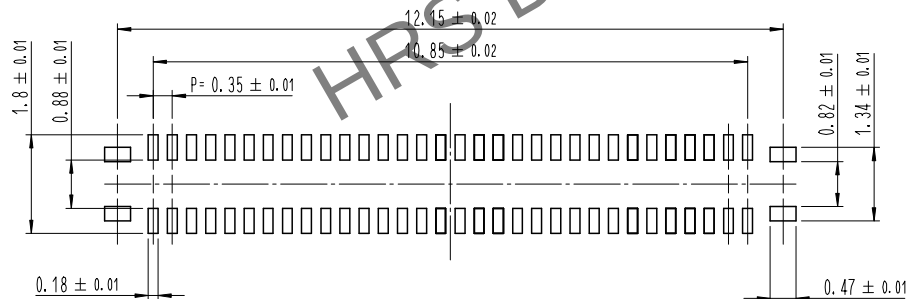
4	PS	CLEAR (EMBOSSED CARRIER TAPE)						
3	COPPER ALLOY			7	PS	CLEAR (REINFORCEMENT COLLAR)		
2	COPPER ALLOY			6	PS	BLACK (PLASTIC REEL)		
1	LCP	UL94 V-0, BLACK		5	POLYESTER	CLEAR (COVER TAPE)		
NO.	MATERIAL	FINISH , REMARKS		NO.	MATERIAL	FINISH , REMARKS		
REMARKS				DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
				W. J. LEE 20. 04. 21	W. J. LEE 20. 04. 21	H. W. JO 20. 04. 21	H. W. JO 20. 04. 21	20. 04. 21
CODE NO. (OLD)		DRAWING NO. EDC3-632894-95		PART NO. BM23PF0.8-64DP-0.35V(895)				
	SCALE 10:1							
	UNITS 	HRS HIROSE KOREA CO., LTD.		CODE NO CL 6644-0104-0-895	1/2			

7 RECOMMENDED PCB LAYOUT

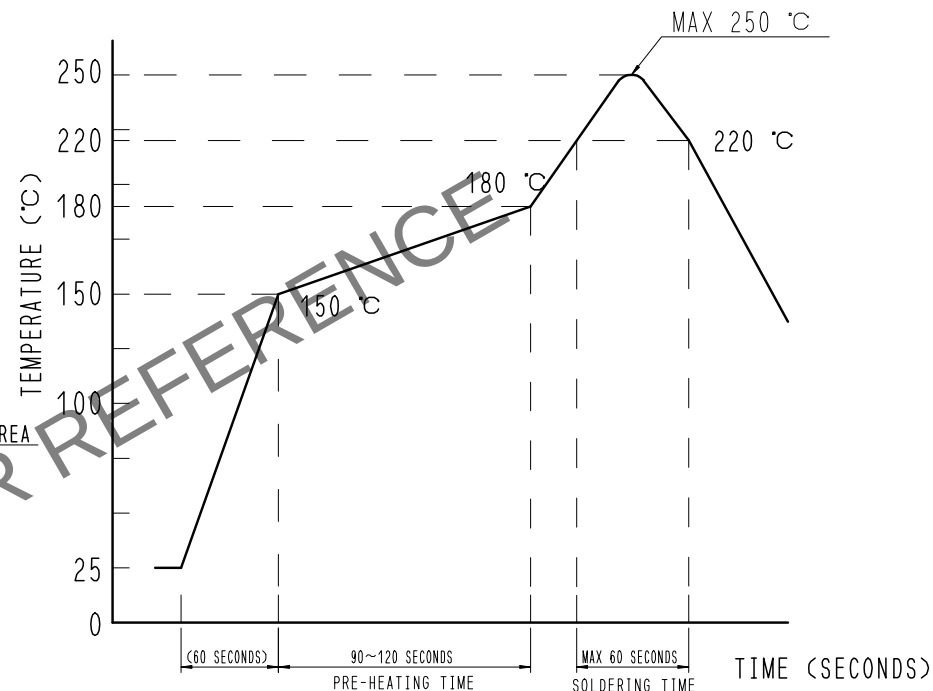


RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : $100 \mu\text{m}$



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N_2 REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220 $^{\circ}\text{C}$: 60 SEC MAX.

(PEAK TEMPERATURE: 250 $^{\circ}\text{C}$ MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE (MIN): 150 $^{\circ}\text{C}$

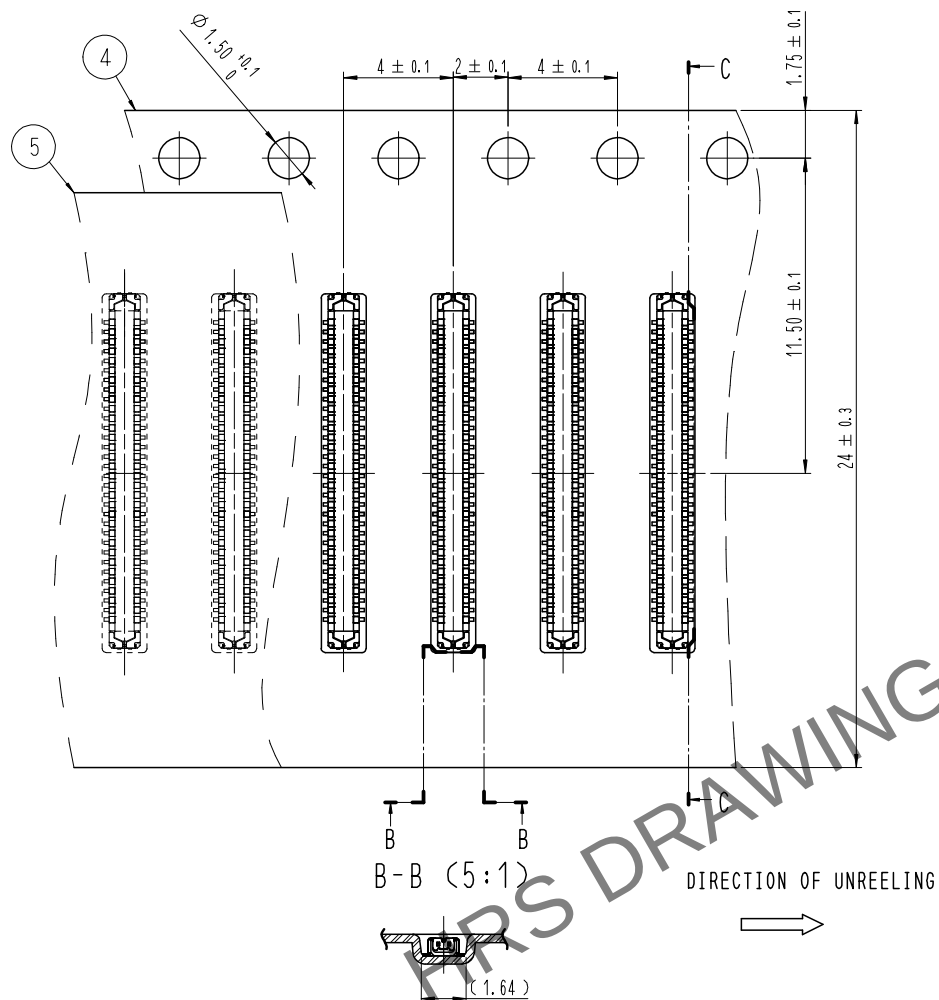
PRE-HEAT TEMPERATURE (MAX): 180 $^{\circ}\text{C}$

PRE-HEAT TIME: 90-120 SEC.

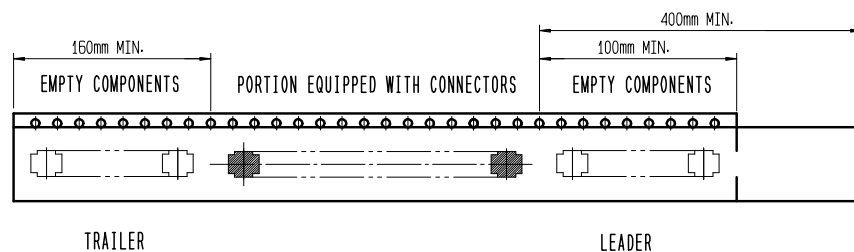
- 6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 7 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-632894-95	PART NO.	BM23PF0.8-64DP-0.35V(895)	
	SCALE	10:1	CODE NO	CL 6644-0104-0-895	2/3
UNITS	HIROSE KOREA CO., LTD.				

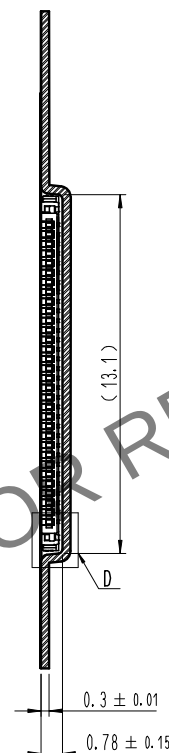
EMBOSSSED CARRIER TAPE PACKAGING (5:1)



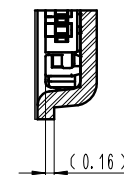
10 TAPING(FREE)



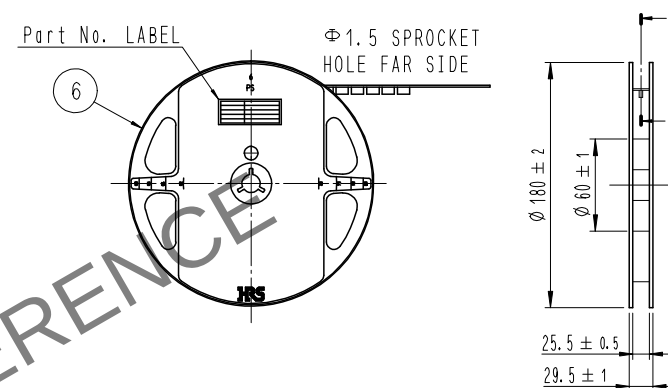
C-C (5:1)



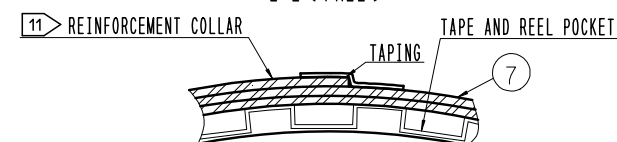
D (10:1)



STYLE AND DIMENTION OF REEL (FREE)



E-E (FREE)



DETAIL OF PART No. LABEL

SUPPLIER	
QUANTITY	
PART NO.	
CODE NO.	
DATE OF MANUFACTURED	
生産月日	年 月 日
図番	*** ** *
品名	BM23PF0.8-64DP-0.35VC89
納入数量	1,000個
納入者	HIROSE KOREA

8 . PER REEL 1,000 CONNECTORS.

9. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

10 REFER TO JIS C 0806, IEC-60286-3 (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)

11. AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER

2. AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET, AND TAPE DOWN AT THE END THE COLLAR.

 SCALE 10:1 UNITS mm	DRAWING NO. EDC3-632894-95		PART NO. BM23PF0.8-64DP-0.35V(895)	
	 HIROSE KOREA CO., LTD.		CODE NO. CL 6644-0104-0-895	3/2